Silicon PNP Epitaxial

HITACHI

Application

- Low frequency power amplifier
- Complementary pair with 2SD667/A

Outline





Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

Item	Symbol	2SB647	2SB647A	Unit
Collector to base voltage	V _{CBO}	-120	-120	V
Collector to emitter voltage	V _{CEO}	-80	-100	V
Emitter to base voltage	V _{EBO}	-5	-5	V
Collector current	I _c	-1	-1	A
Collector peak current	İ _{C(peak)}	-2	-2	A
Collector power dissipation	Pc	0.9	0.9	W
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

Electrical Characteristics (Ta = 25°C)

		2SB647 2SB647A							
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(\text{BR})\text{CBO}}$	-120	—	_	-120	_	—	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	-80	_	_	-100		_	V	$I_c = -1 \text{ mA}, \text{ R}_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(\text{BR})\text{EBO}}$	-5	_	_	-5		—	V	$I_{\rm E} = -10 \ \mu \text{A}, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	—	-10	_	—	-10	μA	$V_{\rm CB} = -100 \text{ V}, I_{\rm E} = 0$
DC current transfer ratio	h_{FE1}^{*1}	60	—	320	60	—	200		$V_{ce} = -5 V,$ $I_c = -150 mA^{*2}$
	h_{FE2}	30	—	—	30	_	—		$V_{ce} = -5 V,$ $I_c = -500 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	—	-1	—	_	-1	V	$I_{c} = -500 \text{ mA},$ $I_{B} = -50 \text{ mA}^{*2}$
Base to emitter voltage	V_{BE}	_	_	-1.5	_	—	-1.5	V	$V_{ce} = -5 V,$ $I_c = -150 mA^{*2}$
Gain bandwidth product	f_{τ}	_	140	_	_	140	_	MHz	$V_{ce} = -5 \text{ V}, \text{ I}_{c} = -150 \text{ mA}$
Collector output capacitance	Cob	_	20	_	_	20	_	pF	$V_{CB} = -10 \text{ V}, I_E = 0$ f = 1 MHz
Notes: 1. The 2SB647 and 2SB647A are grouped by h _{FE1} as follows.									

Notes: 1. The 2SB647 and 2SB647A are grouped by h_{FE1} as follows.

2. F	Pulse test		
	В	C	D
2SB647	60 to 120	100 to 200	160 to 320
2SB647A	60 to 120	100 to 200	—



HITACHI



Unit: mm



Hitachi Code	TO-92 Mod
JEDEC	_
EIAJ	Conforms
Weight (reference value)	0.35 g

Cautions

- Hitachi neither warrants nor grants licenses of any rights of Hitachi's or any third party's patent, copyright, trademark, or other intellectual property rights for information contained in this document. Hitachi bears no responsibility for problems that may arise with third party's rights, including intellectual property rights, in connection with use of the information contained in this document.
- 2. Products and product specifications may be subject to change without notice. Confirm that you have received the latest product standards or specifications before final design, purchase or use.
- 3. Hitachi makes every attempt to ensure that its products are of high quality and reliability. However, contact Hitachi's sales office before using the product in an application that demands especially high quality and reliability or where its failure or malfunction may directly threaten human life or cause risk of bodily injury, such as aerospace, aeronautics, nuclear power, combustion control, transportation, traffic, safety equipment or medical equipment for life support.
- 4. Design your application so that the product is used within the ranges guaranteed by Hitachi particularly for maximum rating, operating supply voltage range, heat radiation characteristics, installation conditions and other characteristics. Hitachi bears no responsibility for failure or damage when used beyond the guaranteed ranges. Even within the guaranteed ranges, consider normally foreseeable failure rates or failure modes in semiconductor devices and employ systemic measures such as fail-safes, so that the equipment incorporating Hitachi product does not cause bodily injury, fire or other consequential damage due to operation of the Hitachi product.
- 5. This product is not designed to be radiation resistant.
- 6. No one is permitted to reproduce or duplicate, in any form, the whole or part of this document without written approval from Hitachi.
- 7. Contact Hitachi's sales office for any questions regarding this document or Hitachi semiconductor products.



Semiconductor & Integrated Circuits. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109 NorthAmerica URL http:semiconductor.hitachi.com/ http://www.hitachi-eu.com/hel/ecg Europe http://www.has.hitachi.com.sg/grp3/sicd/index.htm http://www.hitachi.com.tw/E/Product/SICD_Frame.htm Asia (Singapore) Asia (Taiwan) Asia (HongKong) http://www.hitachi.com.hk/eng/bo/grp3/index.htm http://www.hitachi.co.jp/Sicd/indx.htm Japan For further information write to: Hitachi Semiconductor Hitachi Europe GmbH Hitachi Asia Pte. Ltd. (America) Inc. Electronic components Group 16 Collyer Quay #20-00 179 East Tasman Drive, Dornacher Stra§e 3 Hitachi Tower San Jose,CA 95134 D-85622 Feldkirchen, Munich Singapore 049318 Tel: <1> (408) 433-1990 Fax: <1>(408) 433-0223 Germany Tel: 535-2100 Tel: <49> (89) 9 9180-0 Fax: 535-1533 Fax: <49> (89) 9 29 30 00

 Fax: <49> (89) 9 29 30 00
 Hita

 Hitachi Europe Ltd.
 Hita

 Electronic Components Group.
 Taip

 Whitebrook Park
 3F,

 Lower Cookham Road
 Tun

 Maidenhead
 Tel:

 Berkshire SL6 8YA, United Kingdom
 Fax

 Tel: <44> (1628) 585000

 Fax: <44> (1628) 778322

Hitachi Asia Ltd. Taipei Branch Office 3F, Hung Kuo Building. No.167, Tun-Hwa North Road, Taipei (105) Tel: <886> (2) 2718-3666 Fax: <886> (2) 2718-8180

HITACHI

Hitachi Asia (Hong Kong) Ltd. Group III (Electronic Components) 7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Tsim Sha Tsui, Kowloon, Hong Kong Tel: <852> (2) 735 9218 Fax: <852> (2) 730 0281 Telex: 40815 HITEC HX

Copyright ' Hitachi, Ltd., 1999. All rights reserved. Printed in Japan.